

BGA THERMAL SOLUTIONS MATRIX

The following table represents Wakefield's recommendations for a variety of standard BGA sizes. However, this is by no means a complete list of components that can be used with these heat sinks. To determine suitability for your particular component, request a BGA heat sink evaluation kit.

BGA Sizes (mm)	Heat Sink Footprint (mm)	Heat Sink Height (inches)	Recommended Series #	Attachment Method
17	17 x 17	.40	D10650	Adhesive
19	19 x 19	1.00	602	Adhesive
21	21 x 21	.40	D10850	Adhesive
21	21 x 21	.25 .35 .45 .60	624	Adhesive
23	22 x 22	.40 .60	604	Adhesive
23	22 x 22	.75	605	Adhesive
25	25 x 25	.25 .35 .45 .60	625	Adhesive
27	28 x 28	.25 .35 .45 .60	658	Adhesive
29	30 x 30	.77	606	Adhesive
31	31 x 28	.65	607	Adhesive
31	31 x 31	.80	611	Adhesive
33	32 x 32	.35 .40	610	Adhesive
35	35 x 35	.65	612	Adhesive
35	35 x 35	.25 .35 .45 .60	642	Adhesive
35	35 x 35	.25 .35 .45 .60	630	Adhesive
37.5	37 x 37	.50	613	Adhesive
37.5	37 x 37	.65	659	Adhesive
45.7 x 35.5	37 x 47	.80	617	Adhesive
40	38 x 38	.30 .50 1.00	614	Adhesive
37.5	38 x 38	.29	660	Adhesive
40	40 x 28	.35	643	Clip
40	40 x 40	.26 .53	655	Adhesive
42.5	41 x 41	.41	615	Adhesive
45	43 x 43	.20 .25 .35 .45 .60	628	Adhesive
45	43 x 43	.15	662	Adhesive
47.5	47 x 47	.80	616	Adhesive
50	50 x 50	.40 .65 .80 1.00	698	Adhesive
50	51 x 51	.20 1.00	618	Adhesive
50	52 x 51	.80	622	Adhesive
50	53 x 47	.40 .65 .80 1.00	798	Adhesive
50	64 x 51	.24	620	Adhesive
up to 45	73 x 50	.50 1.00	609	Clip
up to 45	73 x 50	.95	619	Clip

RoHS COMPLIANCE

Please note that Wakefield part numbers designated with an "E" in this catalog denote new parts in compliance with the RoHS initiative, with the exception of our Precision Clamps. Wakefield will still continue to offer non-RoHS compliant versions of these parts. Please be aware that many Wakefield Standard parts have always been compliant since their design inception and therefore will not carry the "E" designation.

Wakefield requests that you refer to the RoHS compliance tool on our website at www.wakefield.com to verify RoHS compliance. If you require further clarification or information regarding RoHS, please contact the factory.



THERMAL INTERFACE MATERIAL PART NUMBER GUIDE

All of the heat sinks shown in this catalog are available with any of the following thermal tape and interface materials, pre-applied at the factory. Use the "T" series, thermally enhanced, pressure sensitive adhesives to attach the heat sink to the electronic package and provide a good thermal link to the heat sink. The "S" series interface materials have adhesives on only one side, for pre-attachment to the heat sink, and provide superior thermal performance. Specify these materials in applications where the heat sink will be fixed to the electronic package by some mechanical means other than a tape. Please note that none of these materials are for use in applications requiring electrical isolation from the electronic device. All options other than -T1 and -T4 are RoHS compliant.

Note: To obtain the estimated thermal resistance of the interface material in your application, divide the thermal impedance value by the area of the pad in square inches. For example, a 2" x 2" piece of T4 has a resistance of 1.10 C-in^2/W \div 4 in^2=0.275 C/W

Suffix	Manufacturer Product	Thermal Impedance C-in^2/W	Thickness, Inches	Package Surface, Comments
-T1	Chomerics, T405	0.47	0.006	Metal/ceramic; aluminum carrier
-T1E	Chomerics, T405R	0.47	0.006	RoHS-compliant version of -T1
-T3	Chomerics, T412	0.25	0.009	Metal/ceramic; very good performance and conformity
-T4	Chomerics, T410	1.10	0.007	Plastic
-T4E	Chomerics, T410R	1.10	0.007	RoHS-compliant version of -T4
-T5	Chomerics, T411	1.00	0.011	Plastic; conforms to out-of-flat packages
-T6	3M, 8810	0.88	0.010	Metal/ceramic; very good adhesion and conformity
-T7	Bergquist, BP 108	1.28	0.008	Metal/ceramic; electrically insulating

"T" SERIES THERMALLY ENHANCED PRESSURE SENSITIVE ADHESIVES

"S" SERIES THERMAL INTERFACE PADS

Suffix	Manufacturer Product	Thermal Impedance C-in^2/W	Thickness, Inches	Package Surface, Comments
-S4	Berquist Softface	0.06	0.005	All surfaces; requires mechanical fasteners

ORDERING INFORMATION

Once you have chosen heat sink and thermal interface material that meets your thermal & mechanical requirements it is easy to designate the part number. Simply add the interface material suffix referenced on the chart above to the base part number for the heat sink. The base part number already includes information regarding its size and finish.

Example:

To order the 658 Series heat sink at .350" tall with the T5 thermal interface material, specify part number:

<u>658-35AB - T5</u>

From Catalog Page ?? -

— From Table on Page ??





٦	624 SERIES	Omnidirectional Pin Fin He	at Sink for BGAs		
	Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight Ibs. (grams)
	624-25AB	.827 (21)	.250 (6.4)	21mm BGA	.009 (4.09)
	624-35AB	.827 (21)	.350 (8.9)	21mm BGA	.011 (4.99)
î	624-45AB	.827 (21)	.450 (11.4)	21mm BGA	.015 (6.81)
	624-60AB	.827 (21)	.600 (15.2)	21mm BGA	.026 (11.80)

Material: Aluminum, Black Anodized

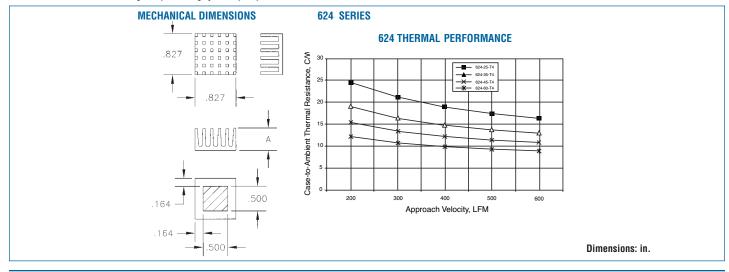
The 624 Series is an omnidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

PRODUCT FEATURES

• Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.

Available with pressure sensitive adhesives for quick and easy mounting. See Page 3



625 SERIES **Omnidirectional Pin Fin Heat Sink for BGAs**

Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight Ibs. (grams)
625-25AB	.984 (25)	0.250 (6.4)	25 mm BGA	.012 (5.45)
625-35AB	.984 (25)	0.350 (8.9)	25 mm BGA	.014 (6.36)
625-45AB	.984 (25)	0.450 (11.4)	25 mm BGA	.018 (8.17)
625-60AB	.984 (25)	0.600 (15.2)	25 mm BGA	.030 (13.62)
Motorial: Aluminum	Plack Anadizad			

Material: Aluminum, Black Anodized

The 625 Series is an omnidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).



PRODUCT FEATURES Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60

- inch.
- Available with pressure sensitive adhesives for quick and easy mounting. See Page 3

MECHANICAL DIMENSIONS 625 SERIES **625 THERMAL PERFORMANCE** C∖V 20 984 18 Case-to-Ambient Thermal Resistance, 16 14 MM А 12 .984 4 10 8 .117 6 2 750 200 300 400 500 600 Approach Velocity, LFM Dimensions: in.



	659 SERIES	Unidirectional Fin H	eat Sink for BGAs			
	Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Application	Heat Sink Finish	Weight Ibs. (grams)
(//////)	659-65AB	1.45 (36.8) sq	0.650 (16.5)	37mm BGA	Black Anodized	0.050 (22.68)
	Notes: 1. Optional fa	ctory preapplied pressure-sen	sitive adhesive. See Page 3			· · ·

NATURAL AND FORCED Convection characteristics **MECHANICAL DIMENSIONS** 1.450 (36.8)SQ REF AIR VELOCITY (LFM) HEAT SINK TEMPERATURE RISE ABOVE AMBIENT AIR (°C) THERMAL RESISTANCE SINK TO AMBIENT ('C/WA 60 0.650 (16.5) 63 27 0.004 TIR 0.070 (1.8) REF + 1.450 (36.8) REF + Dimensions: in. (mm) HEAT DISSIPATED (WATTS)

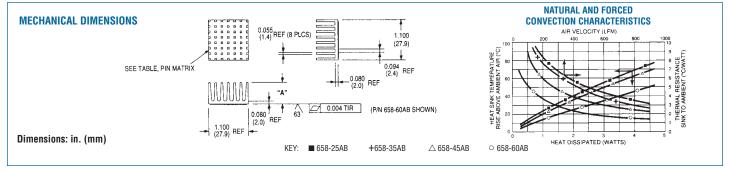
	655 SERI	ES Omnidirection	nal Pin Fin Heat Si	nk for BGAs and P	owerPC™		
Juli Maria	Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Dimension "B" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
	655-26AB 655-53AB	1.600 (40.6) sq 1.600 (40.6) sq	0.260 (6.6) 0.525 (13.3)	0.125 (3.2) 0.145 (3.7)	40mm BGA 40mm BGA	Black Anodized Black Anodized	0.038 (17.01) 0.050 (22.68)
add acount	Notes: 1. Opt.	ional factory preapplied pres	sure-sensitive adhesive.	See Page 3			
MECHANICAL DIMENSIO	NS	1.600 SQ 0.000 0.000 C 0.000 0.000 C 0.000 0.000 C 0.000 0.000 C 0.000 0.000 C 0.000 0.000 C 0.000 C 0.			000 0 200	ATURAL AND FORCED CTION CHARACTERISTIC AIR VELOCITY (LFM) 400 500 600	1000
Dimensions: in. (mm)		.в		WN <u>;</u>	HEAT SINK TEMPERATURE RISC ABOVE AMBIENT AIR ('C)	4 6 8 (EAT DISSIPATED (WATTS)	AMBIENT

658 SERIES Omnidirectional Pin Fin Heat Sink for BGAs and PowerPC™

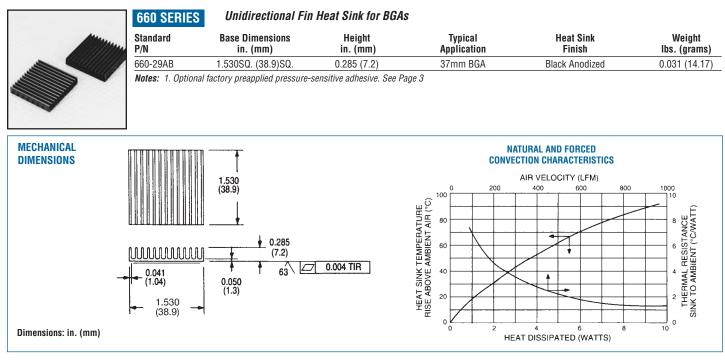


Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
658-25AB	1.100 (27.9) sq	0.250 (6.4)	27mm BGA	Black Anodized	0.013 (5.67)
658-35AB	1.100 (27.9) sq	0.350 (8.9)	27mm BGA	Black Anodized	0.015 (6.70)
658-45AB	1.100 (27.9) sq	0.450 (11.4)	27mm BGA	Black Anodized	0.019 (8.50)
658-60AB	1.100 (27.9) sq	0.600 (15.2)	27mm BGA	Black Anodized	0.031 (14.17)

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HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, and FPBGAs





642 SERIES Unidirectional Fin Heat Sink for BGAs

Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight Ibs. (grams)
642-25AB	1.378 (35)	.250 (6.4)	35 mm BGA	.022 (9.99)
642-35AB	1.378 (35)	.350 (8.9)	35 mm BGA	.027 (12.26)
642-45AB	1.378 (35)	.450 (11.4)	35 mm BGA	.031 (14.07)
642-60AB	1.378 (35)	.600 (15.2)	35 mm BGA	.039 (17.71)

Material: Aluminum, Black Anodized

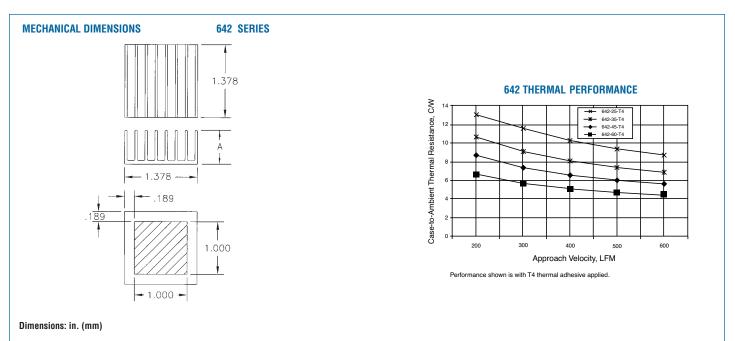
The 642 Series is an unidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

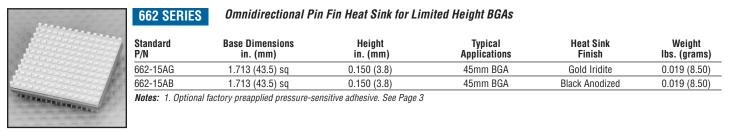
PRODUCT FEATURES

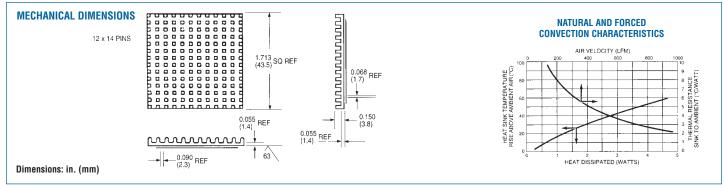
Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.
Available with pressure sensitive adhesives for quick and easy mounting.

See Page 3



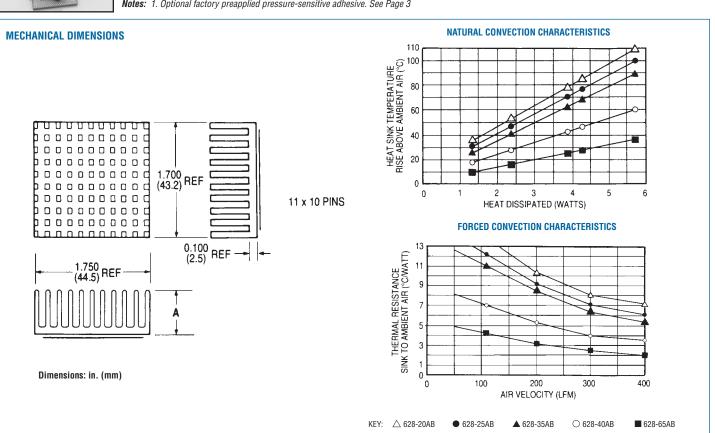
HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, and FPBGAs





	628 SERIES	Omnidirectional Pin Fin	Heat Sink for BGAs			
with Name	Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
	628-20AB	1.750 (44.5) x 1.700 (43.2)	0.200 (5.1)	45mm BGA	Black Anodized	0.031 (14.17)
With the second second	628-25AB	1.750 (44.5) x 1.700 (43.2)	0.250 (6.4)	45mm BGA	Black Anodized	0.038 (17.01)
	628-35AB	1.750 (44.5) x 1.700 (43.2)	0.350 (8.9)	45mm BGA	Black Anodized	0.044 (19.84)
ALL STORY	628-40AB	1.750 (44.5) x 1.700 (43.2)	0.400 (10.2)	45mm BGA	Black Anodized	0.050 (22.68)
and the second se	628-65AB	1.750 (44.5) x 1.700 (43.2)	0.650 (16.5)	45mm BGA	Black Anodized	0.056 (25.51)
L'and a fer	Notes: 1. Optional fa	actory preapplied pressure-sensitiv	e adhesive. See Page 3			· · · · ·

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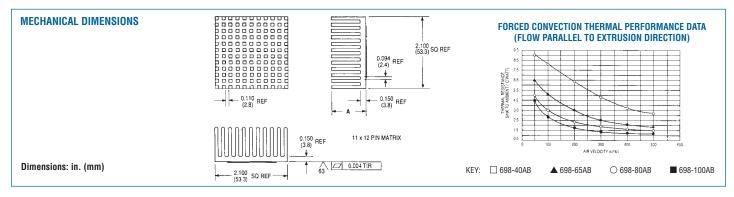


P/N 630 630 630 630 630 630 7 Mat The forc App digit	N 30-25AB 30-35AB 30-45AB 30-60AB laterial: Aluminum, Black And he 630 Series is an omnidirection reed-convection applications. opplications include network rou gital cameras, consumer video usitioning systems (GPS). 630 SERIES	onal pin fin heat sink for bo uters and switches, high-re games, digital video disks	solution printers,	nm) 6.4) 8.9) 1.4) 5.2) PRODUCT FEAT • Available in four s inch. • Available with pre See Page 3	Typical Applications 35mm BGA 35mm BGA 35mm BGA 35mm BGA		
G30 G30 G30 G30 G30 G30 G30 G30 G30 G30	30-35AB 30-45AB 30-60AB laterial: Aluminum, Black And he 630 Series is an omnidirection reed-convection applications. oplications include network rou gital cameras, consumer video sitioning systems (GPS). 630 SERIES	1.378 (35) 1.378 (35) 1.378 (35) odized onal pin fin heat sink for bo uters and switches, high-re- games, digital video disks	.350 (8 .450 (1 .600 (1 oth natural and solution printers, s (DVD) and global	 8.9) 1.4) 5.2) PRODUCT FEA1 Available in four s inch. Available with pre See Page 3 	35mm BGA 35mm BGA 35mm BGA TURES tandard heights, .25 inch ssure sensitive adhesives		.011 (4.99) .015 (6.81) .026 (11.80) inch, and .60
The forc App digit posi MECHANICAL DIMENSIONS	the 630 Series is an omnidirection reed-convection applications. oplications include network rou gital cameras, consumer video ositioning systems (GPS). 630 SERIES	onal pin fin heat sink for bo uters and switches, high-re games, digital video disks	solution printers, (DVD) and global	 Available in four s inch. Available with pre See Page 3 	tandard heights, .25 inch ssure sensitive adhesives		
		;	11	630 THERMA	L PERFORMANCE		
.075 (1.9) REF ——	I I+		11				
	1 1 x 11 PIN MATRIX	T .080 (2.0) REF	Sink-to-Air-Thermal Resistance, CW		400 500 ach Velocity, LFM 35AB - 630-60A	ensions: in.	700

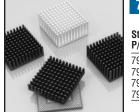
HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, and FPBGAs

~	698 SERIES	Omnidirectional Pi	n Fin Heat Sink For BG	As		
	Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
	698-40AB	2.100 (53.3) sq.	0.400 (10.2) sq.	45mm BGA	Black Anodized	0.075 (34.02)
	698-65AB	2.100 (53.3) sq.	0.650 (16.5) sq.	45mm BGA	Black Anodized	0.119 (53.86)
An An	698-80AB	2.100 (53.3) sq.	0.800 (20.3) sq.	45mm BGA	Black Anodized	0.125 (56.70)
	698-100AB	2.100 (53.3) sq.	1.000 (25.4) sq.	45mm BGA	Black Anodized	0.144 (65.20)

Notes: 1. Optional factory preapplied pressure-sensitive adhesive. See Page 3

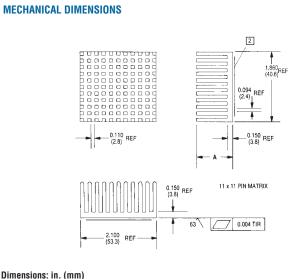


HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, and FPBGAs

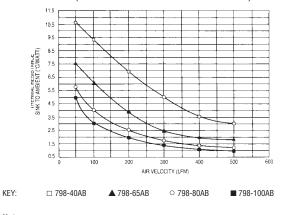


798 SERIES Pin Fin Heat Sink for BGAs	
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Contraction of the second	Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
Aun Vieles	798-40AB	2.100 (53.3) x 1.860 (47.2)	0.400 (10.2)	45mm BGA	Black Anodized	0.063 (28.35)
	798-65AB	2.100 (53.3) x 1.860 (47.2)	0.650 (16.5)	45mm BGA	Black Anodized	0.106 (48.19)
	798-80AB	2.100 (53.3) x 1.860 (47.2)	0.800 (20.3)	45mm BGA	Black Anodized	0.113 (51.03)
	798-100AB	2.100 (53.3) x 1.860 (47.2)	1.000 (25.4)	45mm BGA	Black Anodized	0.131 (59.53)



FORCED CONVECTION THERMAL PERFORMANCE DATA (FLOW PARALLEL TO EXTRUSION DIRECTION)



Notes:

1 . Heat sink mounting surface flatness: 0.004" TIR 2. Optional factory preapplied pressure-sensitive adhesive. See Page 3

Dimensions: in. (mm)



Omnidirectional Pin Fin Heat Sink for BGAs 643 SERIES

	Standard P/N	Base Dimensions in. (mm)	Fin Height in. (mm)	Typical Applications	Weight Ibs. (grams)
ite.	643-35AP	1.60 (40.64) x 1.10 (27.94)	0.350 (8.89)	40 mm BGA	.070 (31.78)

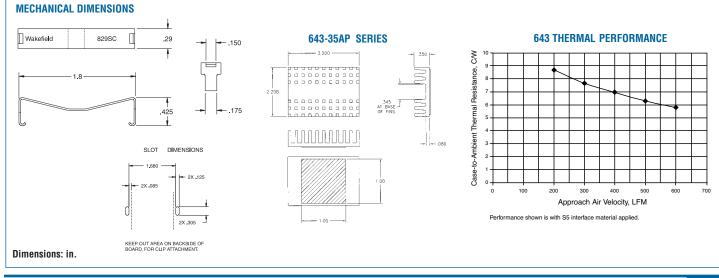
Material: Aluminum, Plain Finish

The Series 643-35AP is an omnidirectional pin fin heat sink for both natural and forced-convection applications designed to fit a 40 mm BGA.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

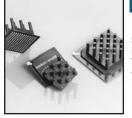
PRODUCT FEATURES

- Available with pressure sensitive adhesives to ensure good thermal performance. See page 3
- Can be ordered with the 829SC clip. Order clip separately. (Clip cannot be purchased without heat sink)





DELTEM™ COMPOSITE HEAT SINKS FOR BGAs



Pin Fin Heat Sink Deltem™ D10650-40

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Weight Ibs. (grams)		
D10650-40	0.650 (16.5) sq	0.400 (10.2)	0.004 (1.91)		
Notes: Available with pressure sensitive adhesives for quick and easy mounting. See Page 3					

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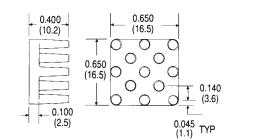
Pin Fin Heat Sink Deltem™ D10850-40

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Applications	Weight Ibs. (grams)
D10850-40	0.850 (21.6) sq	0.400 (10.2)	21mm BGA	0.006 (3.9)
Notes: Available wit	h pressure sensitive adhesives for au	ck and easy mounting. See Page 3		

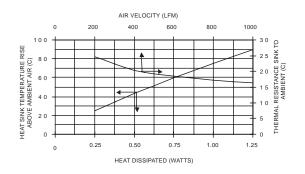
esives for quick and easy mounting. See Page 3

MECHANICAL DIMENSIONS

DELTEM™ D10650-40 PIN FIN HEAT SINK

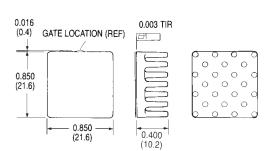


NATURAL AND FORCED CONVECTION CHARACTERISTICS

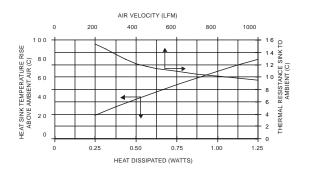




DELTEM™ D10850-40 PIN FIN HEAT SINK



NATURAL AND FORCED CONVECTION CHARACTERISTICS



HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, and FPBGAs

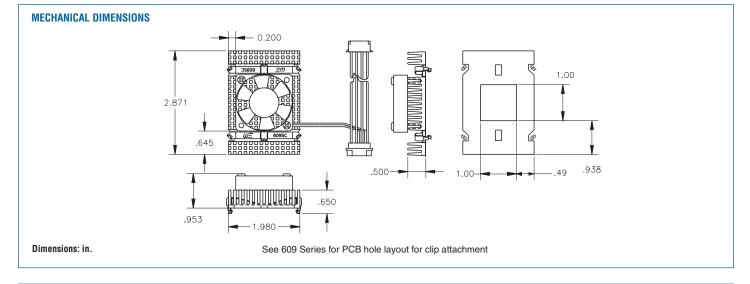
	Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight Ibs. (grams)
	609-50AB 609-100AB	2.895 (73.5) x 2.000 (50.8) 2.808 (71.32) x 1.700 (43.2)	0.500 (12.7) 1.00 (25.4)	40&45mm BGA 40&45mm BGA	Black Anodized Black Anodized	0.094 (42.5) 0.130 (59.0)
	Note: Optional facto S3 (Bergquis	ry preapplied thermal interface ma t Q-Pad 3, 0.14 °C in²/w) t Softface, 0.07 °C in²/w)	· · · · · ·	40040mm Burt	Didok Antodizod	0.100 (00.0)
MECHANICAL DIMENSIO	NS			FORCED CON	VECTION THERMAL PERF	ORMANCE DATA
				(FLOW P	ARALLEL TO EXTRUSION	DIRECTION)
				THERMAL RESISTANCE		
				ENT (°	609-50AB	
μοσουσουσοσου	2.895 (73.5)	2.808		A LAL R MBIE A 1 41 A MBIE 8 609-	100AB	
	2 895 (735)			K TO A		
		PCB 0.062(1.57)			200 300	400 500
	l Sk		PCB THE	ROUGH-HOLE *Performance	AIR VELOCITY (LFM) e is for shrouded condition	ons. 609-100
2.000	"A" -	← "A" □→ DIM.	SLOT 0.087 WIDE 2.720 X 0.158 LONG (69.1)	will perform	better than 609-50 in ca	ses with bypass.
100-01	(609-50AB)	(609-100AB)		>		
	0.610 (15.5)		1.920 (48.8)			
609-50AB HEAT SIN	ĸ	nsions: in. (mm)	± 0 1.920 ↓ (48.8) → 2.720	\rightarrow		
609-50AB HEAT SINI AND CLIP ASSEMBL	(15.5) K Dimer		1.920 (48.8) → 2.720 (69.1) ick PCB	\geq		

619 SERIES Fan Heat Sink for BGA and PowerPC[™] Packages

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Applications	Heat Sink Finish	Thermal Performance	Weight Ibs. (grams)
61995AB124D1	2.871 (72.92) x 1.98 (50.29)	0.953 (24.21)	40&45mm BGA	Black Anodized	1.2° C/W	.150 (68.10)
61995AB054D1	2.871 (72.92) x 1.98 (50.29)	0.953 (24.21)	40&45mm BGA	Black Anodized	1.2° C/W	.150 (68.10)
Note: Optional factory preapplied thermal interface material. See 609 series.						

FEATURES AND BENEFITS:

- . Captivated clips for ease of assembly
- Low acoustic noise
- Impingement air flowAccommodates BGA packages up to 45 mm in size



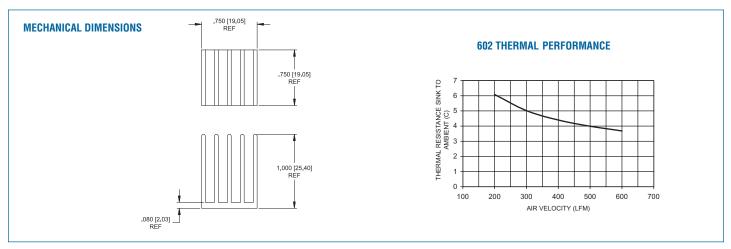


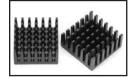


602 SERIES Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
602-100AP	.750 (19.1) sq	1.000 (25.4)	Plain	.021 (9.59)

Material: Aluminum, Plain Finish

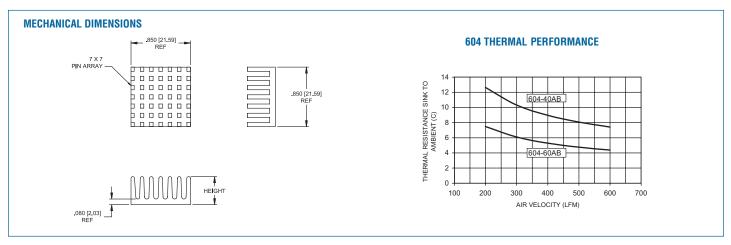




604 SERIES

ES Omnidirectional Pin Fin Heat Sink for BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight Ibs. (grams)
604-40AB	.850 (21.6) sq	.400 (10.2)	Black Anodized	.012 (5.60)
604-60AB	.850 (21.6) sq	.600 (15.2)	Black Anodized	.016 (7.47)





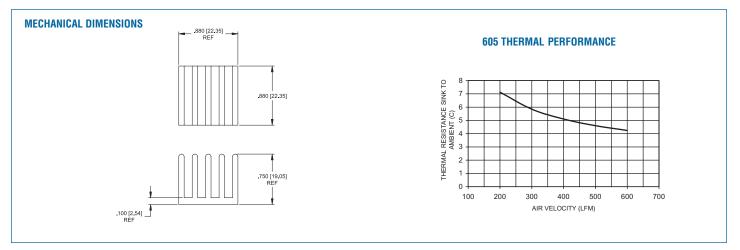
605 SERIES



Unidirectional Fin Heat Sink for BGAs

Standard Base Dimensions Height Heat Sink Weight							
P/N	in. (mm)	in. (mm)	Finish	lbs. (grams)			
605-75AB	.880 (22.4) sq	.750 (19.1)	Black Anodized	.030 (13.5)			

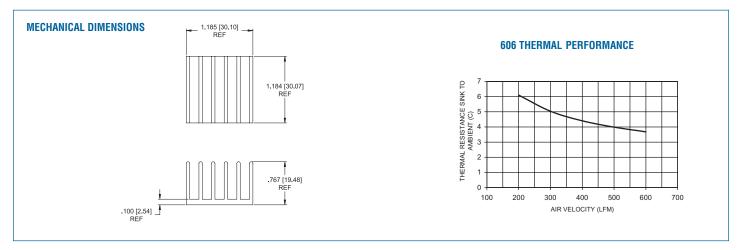
Material: Aluminum, Black Anodized





Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
606-77AB	1.185 (30.1) sq	.767 (19.5)	Black Anodized	.041 (18.7)



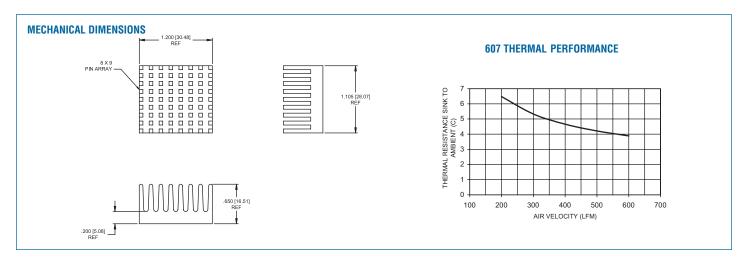


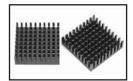


607 SERIES Unidirectional Fin Heat Sink for BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight Ibs. (grams)
607-65AB	1.200 (30.5) x 1.105 (28.1)	.650 (16.5)	Black Anodized	.041 (18.7)

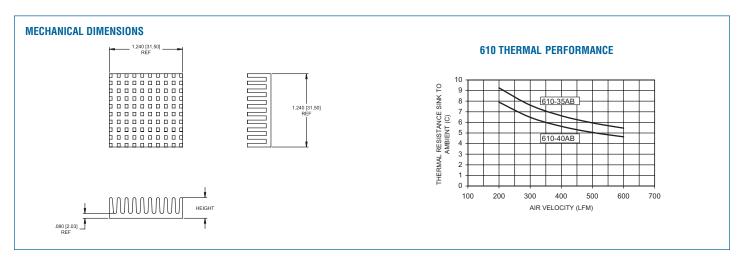
Material: Aluminum, Black Anodized





610 SERIES Omnidirectional Pin Fin Heat Sink for BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight Ibs. (grams)
610-35AB	1.240 (31.5) sq	.350 (8.9)	Black Anodized	.022 (10.0)
610-40AB	1.240 (31.5) sq	.400 (10.2)	Black Anodized	.024 (10.8)





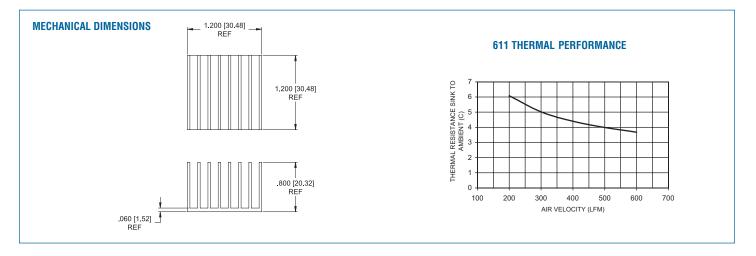
611 SERIES



Unidirectional Fin Heat Sink for BGAs

*				
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight Ibs. (grams)
611-80AB	1.200 (30.5) sq	.800 (20.3)	Black Anodized	.036 (16.3)

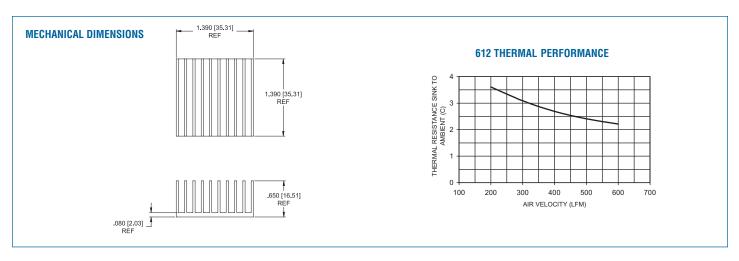
Material: Aluminum, Black Anodized





Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
612-65AB	1.390 (35.3) sq	.650 (16.5)	Black Anodized	.054 (24.5)



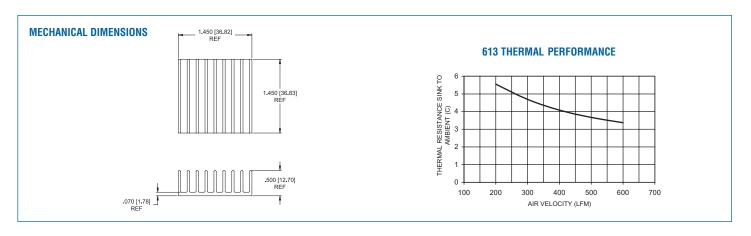




Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
613-50AB	1.450 (36.8) sq	.500 (12.7)	Black Anodized	.046 (20.8)

Material: Aluminum, Black Anodized

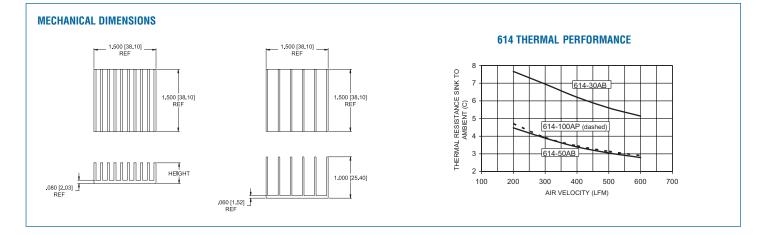




614 SERIES Unidirectional Fin Heat Sink for BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight Ibs. (grams)
614-30AB	1.500 (38.1) sg	.300 (7.6)	Black Anodized	.030 (13.8)
614-50AB	1.500 (38.1) sq	.500 (12.7)	Black Anodized	.048 (21.8)
614-100AP	1.500 (38.1) sq	1.000 (25.4)	Plain	.046 (20.9)

Material: Aluminum, Black Anodized or Plain



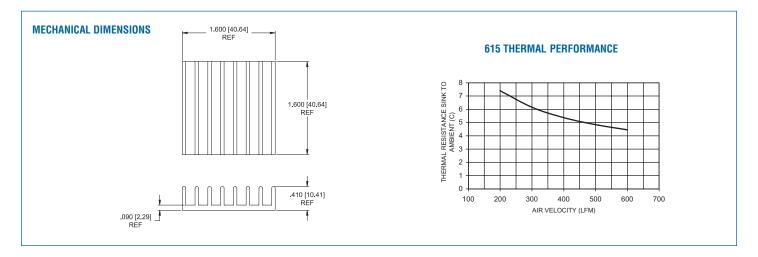




615 SERIES Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
615-41AB	1.600 (40.6) sq	.410 (10.4)	Black Anodized	.046 (21.0)

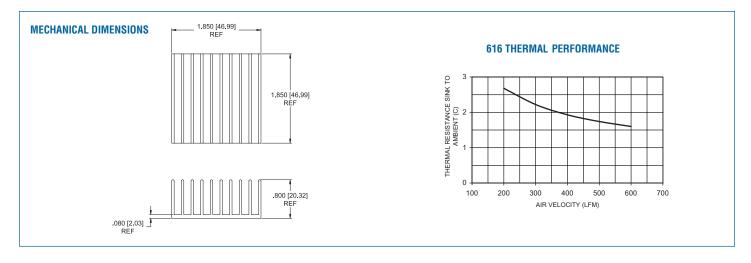
Material: Aluminum, Black Anodized





616 SERIES Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
616-80AB	1.85 (47.0) sq	.800 (20.3)	Black Anodized	.054 (24.5)



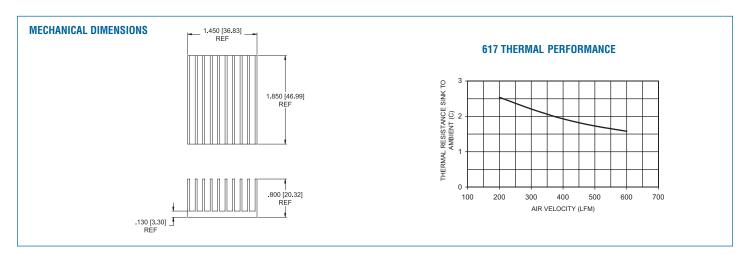




617 SERIES Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
617-80AB	1.450 (36.8) x 1.850 (47.0)	.800 (20.3)	Black Anodized	.082 (37.2)

Material: Aluminum, Black Anodized



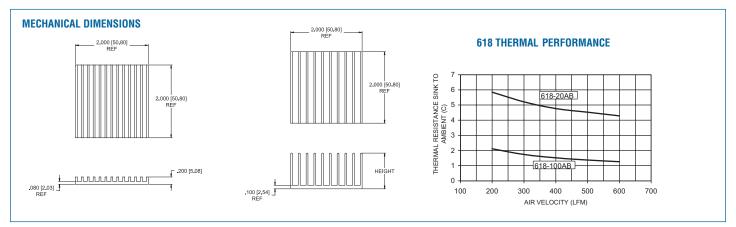
618 SERIES

S Unidirectional Fin Heat Sink for BGAs

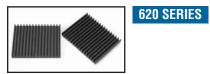
Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
618-20AB	2.00 (50.8) sq	.200 (5.1)	Black Anodized	.046 (21.0)
618-100AP	2.00 (80.8) sq	1.000 (25.4)	Plain	.122 (55.5)

Material: Aluminum, Black Anodized or Plain

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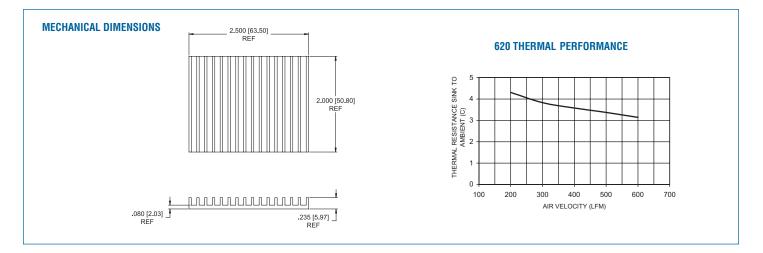




Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
620-24AB	2.500 (63.5) x 2.000 (50.8)	.235 (6.0)	Black Anodized	.063 (28.6)

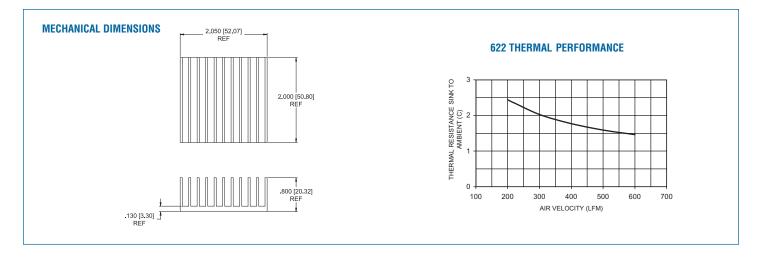
Material: Aluminum, Black Anodized





Unidirectional Fin Heat Sink for BGAs

Standard	Base Dimensions	Height	Heat Sink	Weight
P/N	in. (mm)	in. (mm)	Finish	Ibs. (grams)
622-80AB	2.050 (52.1) x 2.000 (50.8)	.800 (20.3)	Black Anodized	.123 (56.0)





HEAT SINKS FOR MICROPROCESSORS AND ASICS

569, 579, 589, 599 SERIES

Heat Sinks & Clip for Intel's Pentium, Pentium MMX, AMD's K6 & K62, CYRIX's 6x86 & Media GX, Centaur/IDT's WinChip C6

Standard P/N	Base Dimensions in. (mm)	Fin Height in. (mm)	Thermal Resistance at 200 LFM (°C/W)	Interface Material Options
569-100AK	2.34 (59.44) x 2.68 (67.95)	1.00 (25.4)	1.7	Pages 74–76
579-150AK	2.15 (54.71) x 1.95 (49.53)	1.50 (38.10)	1.6	Pages 74–76
589-150AK	2.15 (54.71) x 3.10 (78.74)	1.50 (38.10)	1.5	Pages 74–76
599X-100AB	1.96 (49.78) x 2.67 (67.95)	1.00 (25.4)	1.9	Pages 74–76

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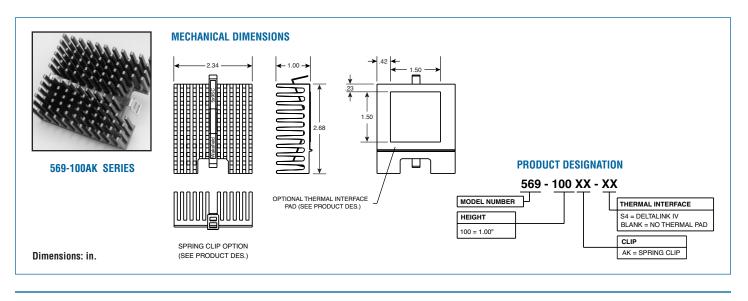
Material: Aluminum, Black Anodized

PRODUCT FEATURES

Compact design heat sinks can comfortably fit a variety of Robust Socket 7-based PC boxes Robust clip attachments

Clips are not captive to sink

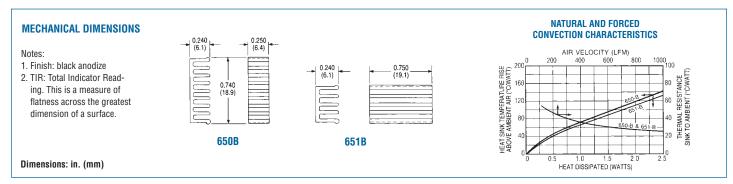
To order heat sink with optional interface material pre-applied at the factory, add S4 or S5 suffix to the part number. (See Product Designation)



	650/651 SERIES Low-Cost Heat Sinks for DIPs and SRAMs					14-16 Pin DIPs	
	Standard P/N	Length in. (mm)	Width in. (mm)	Height in. (mm)	Typical Applications	Weight Ibs. (grams)	
er e	650B	0.250 (6.4)	0.740 (18.9)	0.240 (6.1)	14-Pin, 16-Pin DIP	0.003 (1.36)	
	651B	0.750 (19.1)	0.415 (10.5)	0.240 (6.1)	14-Pin, 16-Pin DIP	0.005 (2.27)	

These extruded heat sinks serve as low-cost heat dissipation solutions for DIPs with pin counts from 14 to 16. Use an epoxy such as Wakefield Engineering DeltaBond[™] 152 or 155, or use Wakefield 2-part DeltaBond[™] 156 modified

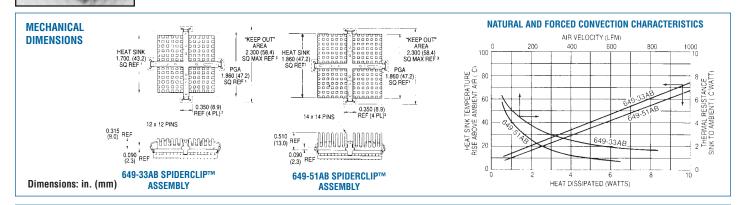
acrylic adhesive. The 650 and 651 are also available in natural aluminum finish. They can be ordered as 650P or 651P.



100

HEAT SINKS FOR MICROPROCESSORS AND ASICS

	649 SERIES	SpiderClip™ H	SpiderClip™ Heat Sink Assembly for Motorola MC68040™, MC68060					
	Standard	Base Dimensions	Height	Base Thickness	Clip	Heat Sink	Weight	
	P/N	in. (mm)	in. (mm)	in. (mm)	Color	Finish	Ibs. (grams)	
	649-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Gray	Black Anodized	0.044 (19.84)	
	649-51AB	1.86 (47.2) sq	0.510 (13.0)	0.090 (2.3)	Gray	Black Anodized	0.056 (25.51)	
ALC: A		· · ·	· · ·	· ·			· · · · · ·	



1111	669 SERIES 661 SERIES						
	Standard P/N	Base Dimensions in. (mm)	Dimensions "A" Height in. (mm)	Base Thickness in. (mm)	Clip Color	Standard Finish	Weight Ibs. (grams)
	669-32AG	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Black	Gold Iridite	0.044 (19.84)
	669-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Black	Black Anodized	0.044 (19.84)
Aller E	669-40AB	1.70 (43.2) sa	0.400 (10.2)	0.090 (2.3)	Black	Black Anodized	0.044 (19.84)
inte pr2	669-52AB	1.70 (43.2) sq	0.520 (13.2)	0.090 (2.3)	Black	Black Anodized	0.050 (22.68)
	661-32AG	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	N/A	Gold Iridite	0.044 (19.84)
	661-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	N/A	Black Anodized	0.044 (19.84)
	661-40AB	1.70 (43.2) sq	0.400 (10.2)	0.090 (2.3)	N/A	Black Anodized	0.044 (19.84)
	661-52AB	1.70 (43.2) sq	0.520 (13.2)	0.090 (2.3)	N/A	Black Anodized	0.050 (22.68)

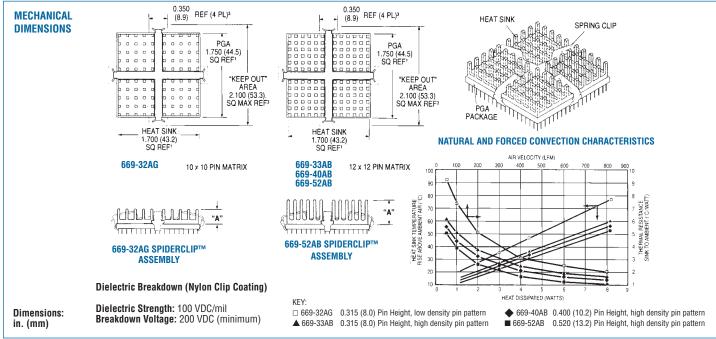
669 Series SpiderClip™ Heat Sink Assemblies may be applied to the following: Intel 82495 Cache Controller

• Intel 80486DX and 80486DX2™ (168 PGA) • AMD AM 29000 Microcontrollers

Intel I960CA, I960CF Enbedded Controllers

 Intel DX4[™] (168 PGA) • Intel 80486SX (168 PGA) and I860XR (208 PGA)

• AMD Am 486 Microprocessors AM486DX2, AM486DX4



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